

MVR5510AMDA4ES – NXP Standard

Configuration for S32G based applications using LPDDR4

Configuration report for ASILD OTP program ID: A4 rev G

Rev. 1.0 - Mar 3 2021

Report

1 General description

The VR5510 is an automotive multi-output power management integrated circuit, with focus on Gateway, V2X and Infotainment applications. It includes multiple high efficiency switch mode and linear voltage regulators. It offers external frequency synchronization input and output, for optimized system EMC performance.

The VR5510 includes enhanced safety features, with fail-safe output, becoming a full part of a safety-oriented system partitioning, covering both ASILB and ASILD safety integrity level. It is developed in compliance with ISO 26262 standard.

2 Features and benefits

- 60V DC maximum input voltage
- Configurable VPRE synchronous buck controller with external MOSFETs.
- Configurable Single/dual-Phase Low voltage buck converters with DVS capability
- Configurable Low voltage integrated synchronous BUCK3 converter
- BOOST converter with integrated low side switch
- 3x linear voltage regulators with configurable Output Voltage
- High voltage linear regulator (HVLDO) with LDO and Switch mode operation
- EMC optimization with frequency tuning, clock synchronization, frequency spread spectrum and slew rate control
- Low power standby mode (40uA quiescent Current)
- 2x input pins for wake-up detection and battery voltage sense
- Device control via I2C interface with CRC (up to 3.4 MHz)
- Selectable OTP Default configuration

3 Applications

- Automotive Infotainment
- High - End Industrial

4 Ordering information

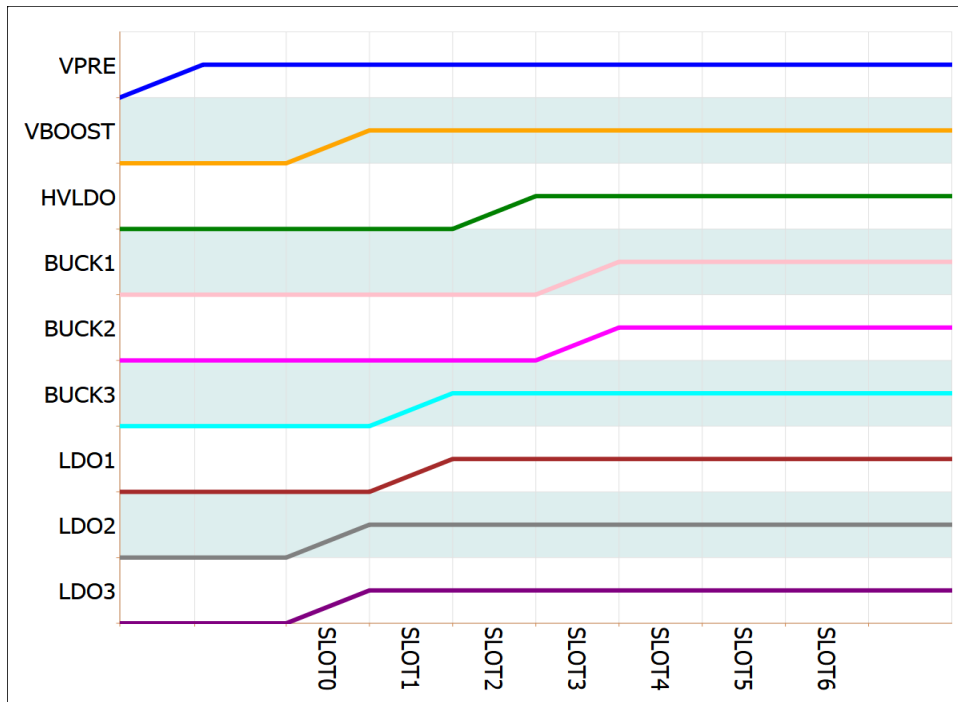
Table 1. Ordering information

Type number ^[1]	Package		
	Name	Description	Version
MVR5510AMDA4ES	QFN56 EP	QFN56 plastic thermally enhanced very thin quad flat non-leaded package. Wettable flanks; 56 terminals; 0.5mm pitch, 8mmx8mmx0.85mm body	SOT684-21

[1] To order parts in tape and reel, add the R2 suffix to the part number.

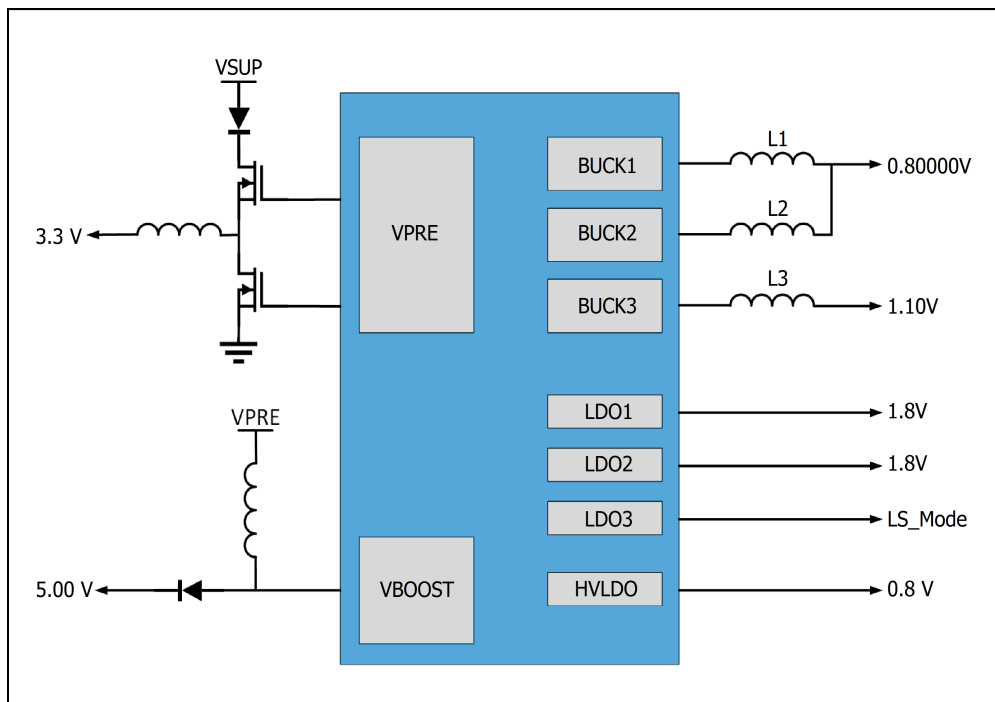


5 Power-up sequence summary



The signals depicted above are enable signals for each regulator. They don't represent the actual ramp voltage

6 Hardware configuration diagram



7 System configuration

See VR5510 datasheet for parametric details. The OTP configuration summary for A4 sequence ID is provided in Tables below.

Table 2. Device OTP configuration

Functional block	Feature	OTP selection
Device Configuration	Main I2C Address	0x20
	VSUP UV threshold	4.9V
	Auto Re-try Enable	Enabled (default)
	Auto Re-try Timeout	4 s (default)
	Number of Retries	Infinite Retry (default)
	PLL Enable	Disabled (default)
	Clock 1 Divider	2.22 MHz (default)
	Clock 2 Divider	455 KHz (default)
	Thermal Warning TH	105 °C (default)
	Deep Sleep Enable	DSM Disabled (default)
IO Configuration	PWRON2 Control	Not Required
	AMUX/FOUT Select	AMUX Enabled (default)
	PSYNC Enable	PSYNC Disabled (default)
	PSYNC Mode	Sync 2 x VR5510
	PSYNC Power Down Ctrl	Ignore for PwrDown
	Standby Transition Timer	Enabled (default)
	Standby Discharge TH	75 mV (default)
	Standby Polarity	Active Low (default)
	Standby PGOOD Enable	Enabled (default)
	PSYNC PGOOD Ext	Disabled

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	Ext Standby Discharge	Disabled
	Standby PGOOD Delay	400us for HVLDO = 3.3V
	VDDIO Supply Seletion	LDO3 (default)
	Multiphase Configuration	Dual Phase

Table 3. Voltage Regulators Configuration

Functional block	Feature	OTP selection
VPRE Configuration	VPRE Voltage	3.3 V (default)
	Slope Compensation	41.4mv/us
	VPRE Standby Output Ctrl	Set by VPREV_STBY (I2C)
	ILIM sense Voltage	120 mV
	VPRE HighSide pull down Slew Rate Ctrl	PD/520mA (455Khz default value)
	VPRE HighSide pull up Slew Rate Ctrl	PU/520mA (455Khz default value)
	VPRE LowSide Slew Rate Ctrl	PU/PD/900mA (default value)
	Soft Start Ramp	2 mV/us (default)
	VPRE Off Time	80 ns
	TON in PFM	550 ns (default value)
	TON Min	45 ns
VBOOST Configuration	Turn OFF Delay	250 us
	VBOOST Voltage	5.00 V (default)
	Slope Compensation	67 mV/μs (default)
	Minimum TON	60 ns (default)
	Current Limit	2.25 A (default)
	Low Side Slew Rate Ctrl	500 V/us (default)
	Input Path to BOS	Enabled (default)

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	PGOOD assert with RSTB	PGOOD Asserts with RSTB Fault (default)
	HVLDO Mode Select	Switch Mode (default)
	WDI Polarity	Falling Edge
	WDI on FCCU1	WDI Disabled (default)
	STANDBY Mode	STANDBY Enabled (default)
	STANDBY Polarity	Active Low in standby mode (default)
	STANDBY Request Path	I2C + STBY Pin Transition (default)
	STANDBY Window	STBY Window Enabled (default)
	WD Init Timeout	1024ms
	Fault Recovery Mode	Enabled
	WD Selection	Challenger WD
	WD Monitoring	WD Enabled (default)
	FCCU Monitoring	FCCU Enabled (default)
	LBIST Enable	LBIST Enabled

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Table 9. Voltage Monitoring

	VMONEN	Voltage	UV_TH	OV_TH	UV Dbnc	OV Dbnc	PGOOD Ctrl	ABIST Ctrl
VCOREMON	Enabled	0.80000V	95.5%	106%	25 us	25 us	PGOOD Assigned	ABIST performed
VDDIOMON	Enabled	3.3 V	95%	105%	25 us	25 us	PGOOD Assigned	ABIST performed
HVLDOMON	Enabled	0.8 V	93%	107%	25 us	25 us	PGOOD Assigned	ABIST performed
VMON1	Enabled	0.8 V	95.5%	106%	25 us	25 us	PGOOD Assigned	ABIST performed
VMON2	Enabled	0.8 V	97.5%	104.5%	25 us	25 us	PGOOD Assigned	ABIST performed
VMON3	Enabled	0.8 V	95%	105%	25 us	25 us	PGOOD Assigned	ABIST performed
VMON4	Enabled	0.8 V	95%	105%	25 us	25 us	PGOOD Assigned	ABIST performed

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Revision History

Date	OTP Rev	OTP Changes compared to rev F
Mar 3 2021	Rev G	<ol style="list-style-type: none">1. BUCK3 Non DVS Ramp: Changed to 3.47mV/us (power up/down) from 10.42mV/us (power up/down)2. Standby PGOOD Release Delay: Changed to 400us from 300us3. LDO1 Sequence: Changed to Slot 1 from Slot 0